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LM555-MIL

SNAS745 - JUNE 2017

LM555-MIL Timer

Technical

Documents

1 Features

- Direct Replacement for SE555/NE555
- Timing from Microseconds through Hours
- Operates in Both Astable and Monostable Modes
- Adjustable Duty Cycle
- Output Can Source or Sink 200 mA
- Output and Supply TTL Compatible
- Temperature Stability Better than 0.005% per °C
- Normally On and Normally Off Output
- Available in 8-pin VSSOP Package

2 Applications

- Precision Timing
- Pulse Generation
- Sequential Timing
- Time Delay Generation
- Pulse Width Modulation
- Pulse Position Modulation
- Linear Ramp Generator

3 Description

Tools &

Software

The LM555-MIL is a highly stable device for generating accurate time delays or oscillation. Additional terminals are provided for triggering or resetting if desired. In the time delay mode of operation, the time is precisely controlled by one external resistor and capacitor. For a stable operation as an oscillator, the free running frequency and duty cycle are accurately controlled with two external resistors and one capacitor. The circuit may be triggered and reset on falling waveforms, and the output circuit can source or sink up to 200 mA or drive TTL circuits.

Support &

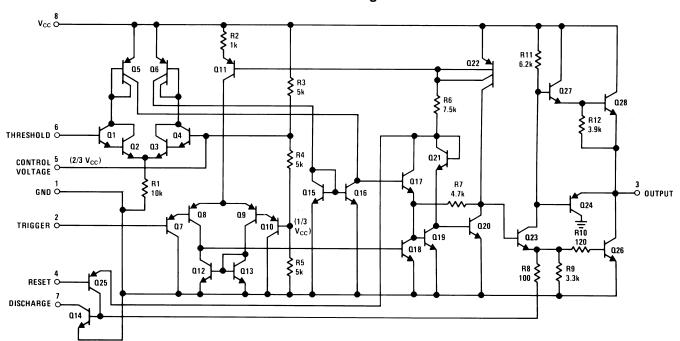
Community

22

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
	SOIC (8)	4.90 mm × 3.91 mm
LM555-MIL	PDIP (8)	9.81 mm × 6.35 mm
	VSSOP (8)	3.00 mm × 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Schematic Diagram

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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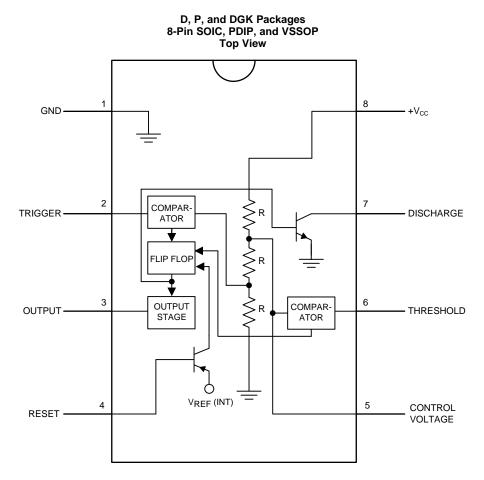
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4 Revision History

DATE	REVISION	NOTES	
June 2017	*	Initial release.	



5 Pin Configuration and Functions



Pin Functions

PIN NO. NAME		- I/O	DESCRIPTION			
		1/0				
5	5 Voltage		Controls the threshold and trigger levels. It determines the pulse width of the output waveform. An external voltage applied to this pin can also be used to modulate the output waveform			
7			Open collector output which discharges a capacitor between intervals (in phase with output). It toggles the output from high to low when voltage reaches 2/3 of the supply voltage			
1	GND	0	Ground reference voltage			
3	Output	0	Output driven waveform			
4	Reset	I	Negative pulse applied to this pin to disable or reset the timer. When not used for reset purposes, it should be connected to VCC to avoid false triggering			
6	Threshold	I	Compares the voltage applied to the terminal with a reference voltage of 2/3 Vcc. The amplitude of voltage applied to this terminal is responsible for the set state of the flip-flop			
2	2 Trigger I		Responsible for transition of the flip-flop from set to reset. The output of the timer depends on the amplitude of the external trigger pulse applied to this pin.			
8	V ⁺	I	Supply voltage with respect to GND			

Specifications 6

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

			MIN	MAX	UNIT
Power Dissipation ⁽³⁾		LM555CM, LM555CN ⁽⁴⁾		1180	mW
Power Dissipa		LM555CMM 613 mW		mW	
Soldering Information	PDIP Package	Soldering (10 Seconds)		260	°C
	Small Outline Packages (SOIC and	Vapor Phase (60 Seconds)		215	°C
internation	VSSOP)	Infrared (15 Seconds)		220	°C
Storage tempe	torage temperature, T _{stg}				°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications. For operating at elevated temperatures the device must be derated above 25°C based on a 150°C maximum junction temperature and a (3)thermal resistance of 106°C/W (PDIP), 170°C/W (S0IC-8), and 204°C/W (VSSOP) junction to ambient.

Refer to RETS555X drawing of military LM555H and LM555J versions for specifications. (4)

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±500 ⁽²⁾	V

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. (1)

The ESD information listed is for the SOIC package. (2)

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply Voltage		18	V
Operating free-air temperature, T _A	0	70	°C
Operating junction temperature, T _J		70	°C

6.4 Thermal Information

			LM555-MIL		
	THERMAL METRIC ⁽¹⁾	PDIP	SOIC	VSSOP	UNIT
		8 PINS	8 PINS	8 PINS	
R ₀	JA Junction-to-ambient thermal resistance	106	170	204	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

 $(T_A = 25^{\circ}C, V_{CC} = 5 \text{ V to } 15 \text{ V}, \text{ unless otherwise specified})^{(1)(2)}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Supply Voltage		4.5		16	V
Supply Current	$V_{CC} = 5 V, R_L = \infty$		3	6	
	V_{CC} = 15 V, R_L = ∞ (Low State) ⁽³⁾		10	15	mA
Timing Error, Monostable					
Initial Accuracy			1 %		
Drift with Temperature	$R_A = 1 \text{ k to } 100 \text{ k}\Omega,$		50		ppm/°C
	$C = 0.1 \ \mu F,^{(4)}$				
Accuracy over Temperature			1.5 %		
Drift with Supply			0.1 %		V
Timing Error, Astable					
Initial Accuracy			2.25		
Drift with Temperature	R_A , $R_B = 1 k$ to 100 k Ω ,		150		ppm/°C
	$C = 0.1 \ \mu F,^{(4)}$				
Accuracy over Temperature			3.0%		
Drift with Supply			0.30 %		N
Threshold Voltage			0.667		x V _{CC}
Trigger Voltage	V _{CC} = 15 V		5		V
	$V_{CC} = 5 V$		1.67		V
Trigger Current			0.5	0.9	μA
Reset Voltage		0.4	0.5	1	V
Reset Current			0.1	0.4	mA
Threshold Current	(5)		0.1	0.25	μA
Control Voltage Level	V _{CC} = 15 V	9	10	11	.,
	$V_{CC} = 5 V$	2.6	3.33	4	V
Pin 7 Leakage Output High			1	100	nA
Pin 7 Sat ⁽⁶⁾					
Output Low	V _{CC} = 15 V, I ₇ = 15 mA		180		mV
Output Low	V _{CC} = 4.5 V, I ₇ = 4.5 mA		80	200	mV
Output Voltage Drop (Low)	V _{CC} = 15 V				
	I _{SINK} = 10 mA		0.1	0.25	V
	I _{SINK} = 50 mA		0.4	0.75	V
	I _{SINK} = 100 mA		2	2.5	V
	I _{SINK} = 200 mA		2.5		V
	$V_{CC} = 5 V$				
	I _{SINK} = 8 mA				V
	I _{SINK} = 5 mA		0.25	0.35	V

(1) All voltages are measured with respect to the ground pin, unless otherwise specified.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Recommended Operating Conditions indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensures specific performance limits. This assumes that the device is within the Recommended Operating Conditions. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.

(3) Supply current when output high typically 1 mA less at $V_{CC} = 5 V$.

(4) Tested at $V_{CC} = 5$ V and $V_{CC} = 15$ V.

(5) This will determine the maximum value of $R_A + R_B$ for 15 V operation. The maximum total ($R_A + R_B$) is 20 M Ω .

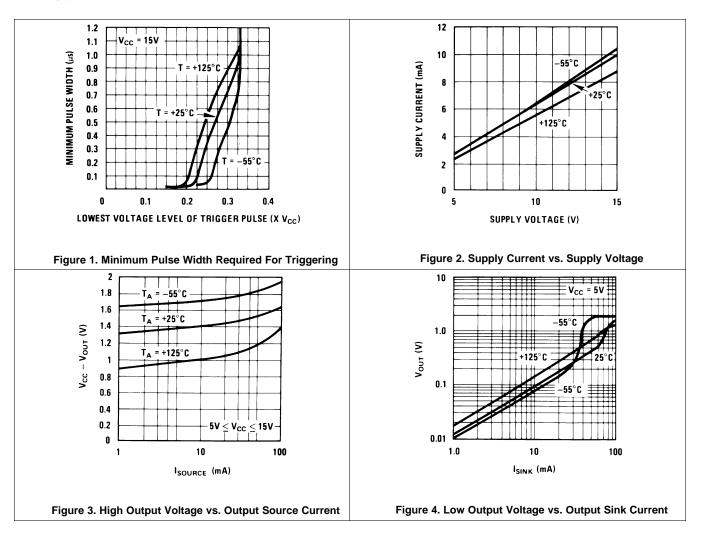
(6) No protection against excessive pin 7 current is necessary providing the package dissipation rating will not be exceeded.

Electrical Characteristics (continued)

 $(T_A = 25^{\circ}C, V_{CC} = 5 \text{ V to } 15 \text{ V}, \text{ unless otherwise specified})^{(1)(2)}$

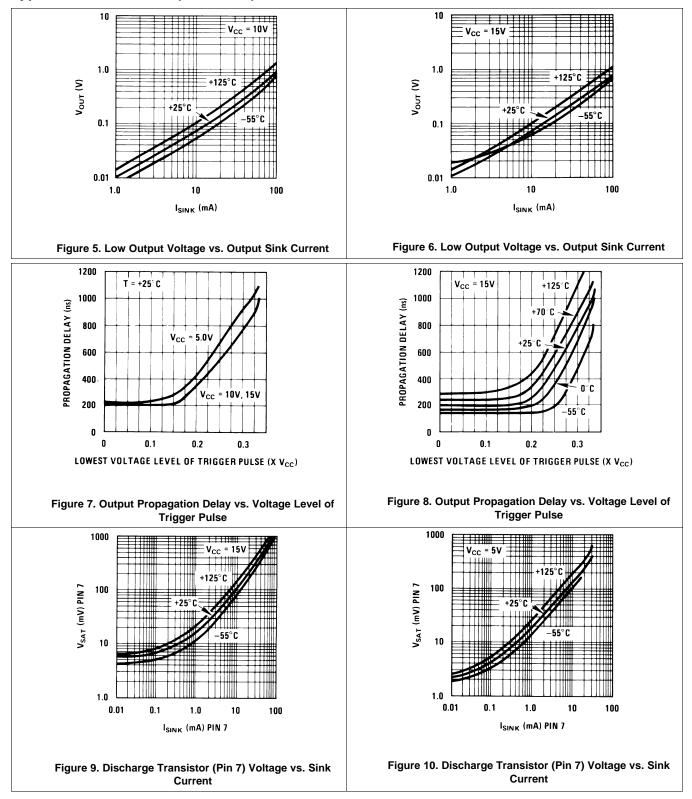
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output Voltage Drop (High)	I_{SOURCE} = 200 mA, V_{CC} = 15 V		12.5		V
	I_{SOURCE} = 100 mA, V_{CC} = 15 V	12.75	13.3		V
	$V_{CC} = 5 V$	2.75	3.3		V
Rise Time of Output			100		ns
Fall Time of Output			100		ns

6.6 Typical Characteristics





Typical Characteristics (continued)

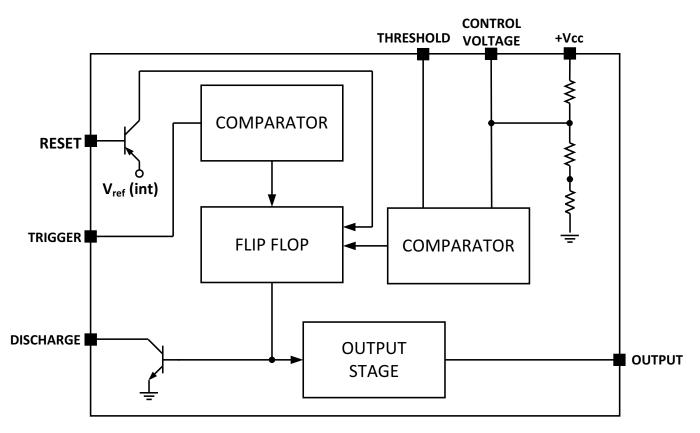


7 Detailed Description

7.1 Overview

The LM555-MIL is a highly stable device for generating accurate time delays or oscillation. Additional terminals are provided for triggering or resetting if desired. In the time delay mode of operation, the time is precisely controlled by one external resistor and capacitor. For astable operation as an oscillator, the free running frequency and duty cycle are accurately controlled with two external resistors and one capacitor. The circuit may be triggered and reset on falling waveforms, and the output circuit can source or sink up to 200 mA or driver TTL circuits. The LM555-MIL are available in 8-pin PDIP, SOIC, and VSSOP packages and is a direct replacement for SE555/NE555.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Direct Replacement for SE555/NE555

The LM555-MIL timer is a direct replacement for SE555 and NE555. It is pin-to-pin compatible so that no schematic or layout changes are necessary. The LM555-MIL come in an 8-pin PDIP, SOIC, and VSSOP package.

7.3.2 Timing From Microseconds Through Hours

The LM555-MIL has the ability to have timing parameters from the microseconds range to hours. The time delay of the system can be determined by the time constant of the R and C value used for either the monostable or astable configuration. A nomograph is available for easy determination of R and C values for various time delays.

7.3.3 Operates in Both Astable and Monostable Mode

The LM555-MIL can operate in both astable and monostable mode depending on the application requirements.

• Monostable mode: The LM555-MIL timer acts as a "one-shot" pulse generator. The pulse beings when the



Feature Description (continued)

LM555-MIL timer receives a signal at the trigger input that falls below a 1/3 of the voltage supply. The width of the output pulse is determined by the time constant of an RC network. The output pulse ends when the voltage on the capacitor equals 2/3 of the supply voltage. The output pulse width can be extended or shortened depending on the application by adjusting the R and C values.

 Astable (free-running) mode: The LM555-MIL timer can operate as an oscillator and puts out a continuous stream of rectangular pulses having a specified frequency. The frequency of the pulse stream depends on the values of R_A, R_B, and C.

7.4 Device Functional Modes

7.4.1 Monostable Operation

In this mode of operation, the timer functions as a one-shot (Figure 11). The external capacitor is initially held discharged by a transistor inside the timer. Upon application of a negative trigger pulse of less than $1/3 V_{CC}$ to pin 2, the flip-flop is set which both releases the short circuit across the capacitor and drives the output high.

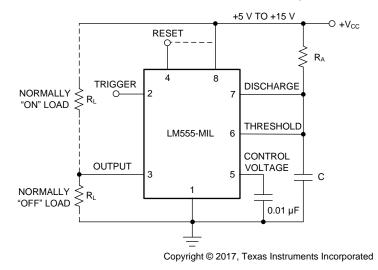


Figure 11. Monostable

The voltage across the capacitor then increases exponentially for a period of $t = 1.1 R_A C$, at the end of which time the voltage equals 2/3 V_{CC}. The comparator then resets the flip-flop which in turn discharges the capacitor and drives the output to its low state. Figure 12 shows the waveforms generated in this mode of operation. Since the charge and the threshold level of the comparator are both directly proportional to supply voltage, the timing interval is independent of supply.

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\square		/		/		f

 $\label{eq:V_CC} \begin{array}{l} \mathsf{V}_{CC} = 5 \ \mathsf{V} \\ \mathsf{TIME} = 0.1 \ \text{ms/DIV}. \\ \mathsf{R}_{\mathsf{A}} = 9.1 \ \mathrm{k}\Omega \\ \mathsf{C} = 0.01 \ \mathrm{\mu}\mathsf{F} \end{array}$

Top Trace: Input 5V/Div. Middle Trace: Output 5V/Div. Bottom Trace: Capacitor Voltage 2V/Div.

Figure 12. Monostable Waveforms

Device Functional Modes (continued)

During the timing cycle when the output is high, the further application of a trigger pulse will not effect the circuit so long as the trigger input is returned high at least 10 μ s before the end of the timing interval. However the circuit can be reset during this time by the application of a negative pulse to the reset terminal (pin 4). The output will then remain in the low state until a trigger pulse is again applied.

When the reset function is not in use, TI recommends connecting the Reset pin to V_{CC} to avoid any possibility of false triggering.

Figure 13 is a nomograph for easy determination of R, C values for various time delays.

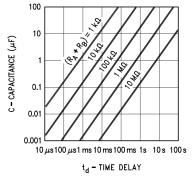
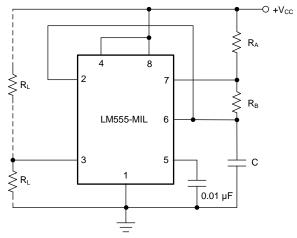


Figure 13. Time Delay

7.4.2 Astable Operation

If the circuit is connected as shown in Figure 14 (pins 2 and 6 connected) it will trigger itself and free run as a multivibrator. The external capacitor charges through $R_A + R_B$ and discharges through R_B . Thus the duty cycle may be precisely set by the ratio of these two resistors.



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Figure 14. Astable

In this mode of operation, the capacitor charges and discharges between 1/3 V_{CC} and 2/3 V_{CC} . As in the triggered mode, the charge and discharge times, and therefore the frequency are independent of the supply voltage.

Figure 15 shows the waveforms generated in this mode of operation.



Device Functional Modes (continued)

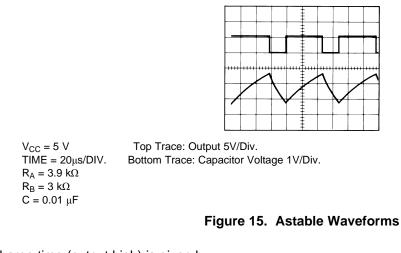




Figure 16 may be used for quick determination of these RC values.

The duty cycle is:

$$\mathsf{D} = \frac{\mathsf{R}_{\mathsf{B}}}{\mathsf{R}_{\mathsf{A}} + 2\mathsf{R}_{\mathsf{B}}}$$



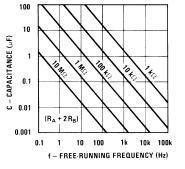


Figure 16. Free Running Frequency

EXAS

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM555-MIL timer can be used a various configurations, but the most commonly used configuration is in monostable mode. A typical application for the LM555-MIL timer in monostable mode is to turn on an LED for a specific time duration. A pushbutton is used as the trigger to output a high pulse when trigger pin is pulsed low. This simple application can be modified to fit any application requirement.

8.2 Typical Application

Figure 17 shows the schematic of the LM555-MIL that flashes an LED in monostable mode.

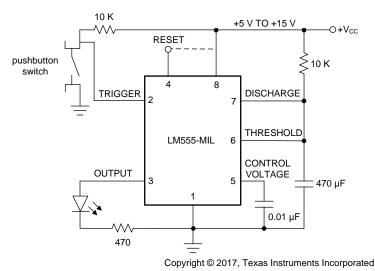


Figure 17. Schematic of Monostable Mode to Flash an LED

8.2.1 Design Requirements

The main design requirement for this application requires calculating the duration of time for which the output stays high. The duration of time is dependent on the R and C values (as shown in Figure 17) and can be calculated by:

$$t = 1.1 \times R \times C$$
 seconds

(6)

8.2.2 Detailed Design Procedure

To allow the LED to flash on for a noticeable amount of time, a 5 second time delay was chosen for this application. By using Equation 6, RC equals 4.545. If R is selected as 100 k Ω , C = 45.4 µF. The values of R = 100 k Ω and C = 47 µF was selected based on standard values of resistors and capacitors. A momentary push button switch connected to ground is connected to the trigger input with a 10-K current limiting resistor pullup to the supply voltage. When the push button is pressed, the trigger pin goes to GND. An LED is connected to the output pin with a current limiting resistor in series from the output of the LM555-MIL to GND. The reset pin is not used and was connected to the supply voltage.

8.2.2.1 Frequency Divider

The monostable circuit of Figure 11 can be used as a frequency divider by adjusting the length of the timing cycle. Figure 18 shows the waveforms generated in a divide by three circuit.



Typical Application (continued)

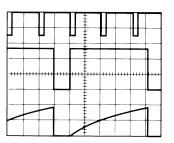


Figure 18. Frequency Divider

8.2.2.2 Additional Information

Lower comparator storage time can be as long as 10 μ s when pin 2 is driven fully to ground for triggering. This limits the monostable pulse width to 10 μ s minimum.

Delay time reset to output is 0.47 µs typical. Minimum reset pulse width must be 0.3 µs, typical.

Pin 7 current switches within 30 ns of the output (pin 3) voltage.

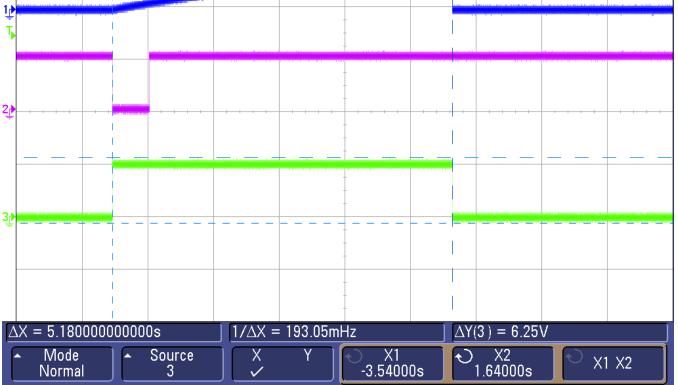
8.2.3 Application Curves

The data shown below was collected with the circuit used in the typical applications section. The LM555-MIL was configured in the monostable mode with a time delay of 5.17 s. The waveforms correspond to:

- Top Waveform (Yellow) Capacitor voltage
- Middle Waveform (Green) Trigger
- Bottom Waveform (Purple) Output

As the trigger pin pulses low, the capacitor voltage starts charging and the output goes high. The output goes low as soon as the capacitor voltage reaches 2/3 of the supply voltage, which is the time delay set by the R and C value. For this example, the time delay is 5.17 s.





0.0s

F

1.000s/

Stop

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3

SNAS745 - JUNE 2017

2

LM555-MIL

5.00V/

1

Typical Application (continued)

5.00V/

5.00V/

4

3

Figure 19. Trigger, Capacitor Voltage, and Output Waveforms in Monostable Mode

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17.3V



9 Power Supply Recommendations

The LM555-MIL requires a voltage supply within 4.5 V to 16 V. Adequate power supply bypassing is necessary to protect associated circuitry. The minimum recommended capacitor value is 0.1 μ F in parallel with a 1- μ F electrolytic capacitor. Place the bypass capacitors as close as possible to the LM555-MIL and minimize the trace length.

10 Layout

10.1 Layout Guidelines

Standard PCB rules apply to routing the LM555-MIL. The 0.1- μ F capacitor in parallel with a 1- μ F electrolytic capacitor should be as close as possible to the LM555-MIL. The capacitor used for the time delay should also be placed as close to the discharge pin. A ground plane on the bottom layer can be used to provide better noise immunity and signal integrity.

Figure 20 is the basic layout for various applications.

- C1 based on time delay calculations
- C2 0.01-µF bypass capacitor for control voltage pin
- C3 0.1-µF bypass ceramic capacitor
- C4 1-µF electrolytic bypass capacitor
- R1 based on time delay calculations
- U1 LMC555

10.2 Layout Example

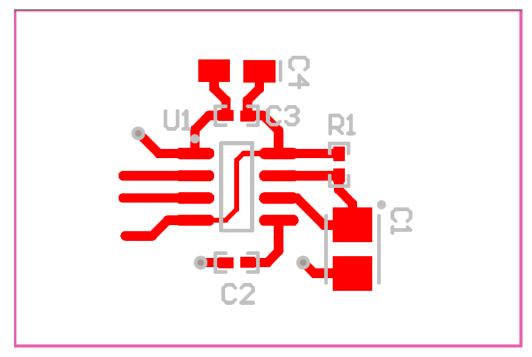


Figure 20. Layout Example

11 Device and Documentation Support

11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.3 Trademarks

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11.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



29-Jun-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM555-MWC	ACTIVE	WAFERSALE	YS	0	1	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 85		Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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